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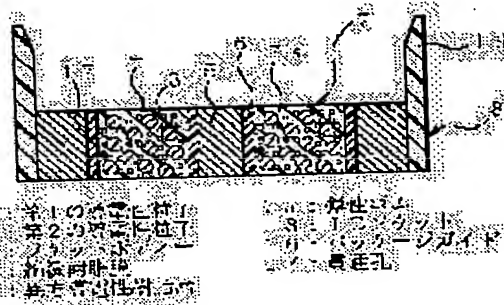
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(54) IC SOCKET

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a suitable IC socket for the electrical characteristic test of a BGA type and an LGA type semiconductor devices.

SOLUTION: In an IC socket 8 which is composed of a socket body 5 made by a metal plate, an anisotropic conductive resin layer 7 applied in a through hole 17 installed at an appointed position of the socket body 5 and a package guide 16 for semiconductor device installed at the periphery of the socket body 5, the anisotropic conductive resin layer 7 is configured by an elastic rubber 7a and first electro-conductive particles 3 and second electro-conductive particles 4, which have different average particle diameters and which are dispersed in the rubber. The socket body 5 and the anisotropic conductive resin layer 7 are insulated with an insulating resin film 6.



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